



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant

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Application No.

10/721,288

Filed

November 26, 2003

Title

INTEGRATED CIRCUIT PACKAGING FOR

IMPROVING EFFECTIVE CHIP-BONDING AREA

Group Art Unit

2824

Examiner

B. Owens

Docket No.

BHT/3183-61

MAIL STOP AMENDMENT

Honorable Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

AMENDMENT

Sir:

In response to the Office Action of October 5, 2004, please amend the above-identified application as follows: